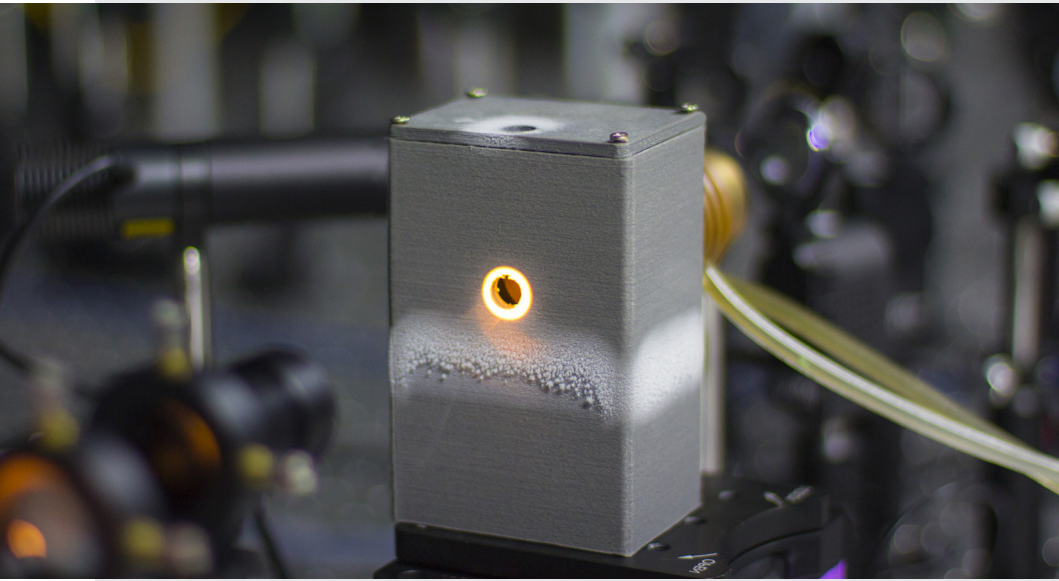
PolyMide™ PA6-GF



Industrial

For other languages, please visit
www.polymaker.com

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Printing with PolyMide™ PA6-GF

PolyMide™ PA6-GF

PolyMide™ PA6-GF is a glass fiber reinforced PA6 (Nylon 6) filament. The material exhibits excellent thermal and mechanical properties without sacrificing the layer adhesion.

Printing settings

Nozzle Temperature:	280-300 ˚C
Bed Temperature:	25-50 ˚C (Do NOT exceed 50 ˚C)
Chamber Temperature:	25-50 ˚C (Do NOT exceed 50 ˚C)
Printing Speed:	60 mm/s
Cooling Fan:	OFF

Note: Settings are based on 0.4 mm nozzle, and may vary with different printers and nozzle diameters.

Bed surface

PolyMide™ PA6-GF can be printed on almost any surface with a thin coat of PVA glue or Magigoo PA. We recommend a flex plate to facilitate the removal of the model from the plate.

Wear resistant nozzle

PolyMide™ PA6-GF contains 25% chopped glass fibers by weight which makes it very abrasive. It is important to have an abrasion resistant nozzle.

Nozzles can come in many different materials, from soft to hard:

Brass
Nickel plated copper
Steel
Stainless steel
Tool steel
Tungsten-carbide
Ceramic/Metal hybrid

PolyMide™ PA6-GF can easily damage a brass nozzle after a few hundred grams of printing. Hardened nozzles, whilst abrasion resistant, are more expensive. Therefore, it is important to consider the cost of investing in a hardened nozzle, the potential frequency of use and scale of the print project.

Note: Brass nozzle will give a better thermal conductivity than hardened nozzle such as stainless steel.

High temperature hot end

We recommend a full-metal hot end that can maintain a stable temperature of at least > 280 ˚C.

Annealing PolyMide™ PA6-GF parts

We reccomend annealing all models printed in PolyMide™ PA6-GF. This allows users to take advantage of the full mechanical and thermal properties of this material.

The annealing process consists of putting the model in an oven at 90˚C for 2 hours.

Support material

PolyDissolve™ S1 is the recommended support material for PolyMide™ PA6-GF. For more information, please visit www.polymaker.com

When using PolyMide™ PA6-GF as a self-support, it is important to remove the support structure right after printing.

Leaving the part exposed to atmospheric moisture may result in strong bonding between the support and printed part, making support removal difficult.

Feeding system

PolyMide™ PA6-GF is a very stiff filament so it is required to have a good set up to ensure a good feeding. For example we recommend avoiding excessive bending in the filament guide system.

Dry box system

PolyMide™ PA6-GF is a polyamide 6 based material which makes it very hygroscopic. This means that it is susceptible to absorbing moisture from the atmosphere which can subsequently affect the quality and mechanical properties of the final prints.

We recommend storing PolyMide™ PA6-GF in a PolyBox™ to prevent moisture absorption. If the filament has absorbed moisture it can be dried at 80˚C for 12 hours in a convection oven.

Note: Polymaker provides the filament with the right moisture amount, having a filament with an extremely low moisture content can affect its processability.

PCP: Profile Creation Process

The profile creation process (PCP) allows users to rapidly develop a printing profile for any given material/printer. During this process is important to consider all of these factors to build a successful profile.

Geometry
Material
Printer
Environment
Purpose

Polymaker developed the PCP to assist customers in creating their own tailored print profiles; taking into account the material, printer, environment as well as the models geometry and purpose. Additionally, the PCP allows individuals to develop their own knowledge and troubleshooting skills.

The PCP is available on www.polymaker.com

The PCP is divided in 5 steps:

It uses less than 300g of materials and less than 7h of working time.

Step 1: Extrusion Flow
Step 2: Flow Management
Step 3: Cooling Fan
Step 4: Warpage
Step 5: Fine Details

Each of these steps has a specific objective and introduces an important concept about the FFF 3D printing process. Each step will also give you the possibility to push your test further for more accurate results.

PolyMide™ Family

	Heat deflection temp. ASTM D648 (ISO 75)	
	1.80 Mpa HDT-A	**0.45 Mpa HDT-B**
PolyMide™ PA6-CF	196 ˚C	215 ˚C
PolyMide™ PA6-GF	124 ˚C	191 ˚C
Unreinforced PA6	80 ˚C	96 ˚C
PolyMide™ CoPA	71 ˚C	91 ˚C

	Young's modulus ASTM D638 (ISO 527, GB/T 1040)	Charpy impact resistance ASTM D256 (ISO 179, GB/T 1043)
PolyMide™ PA6-CF	7453 Mpa	13.3 kJ/m^2
PolyMide™ PA6-GF	4431 Mpa	16.5 kJ/m^2
Unreinforced PA6	2621 Mpa	9.9 kJ/m^2
PolyMide™ CoPA	2223 Mpa	9.6 kJ/m^2

Note: Tested with 3D printed specimens.

Fiber Adhesion™ Technology

Fiber Adhesion technology dramatically improves the Z-axis strength, via engineering the surface chemistry of the fibers to achieve a strong fiber/matrix bonding.

In contrast to conventional fiber-reinforced filaments, which exhibit considerable reduction in Z-axis strength, PolyMide™ PA6-GF provides a higher interlayer adhesion compared to unreinforced PA6.

Layer adhesion

Tensile strength
(Z axis)
ASTM D638
(ISO 527, GB/T 1040)

Unreinforced PA6
53.2Mpa
PolyMide™ PA6-CF
67.7Mpa
+27%

Unreinforced PA6
53.2Mpa
PolyMide™ PA6-GF
61.4Mpa
+15%

Competitor 1

35% CF by weight

PA12
48 Mpa
PA12-CF
28.9 Mpa
-40%

Competitor 2

20% CF by weight

PA6/66
23 Mpa
PA6/66-CF
18 Mpa
-40%

Competitor 3

20% GF by weight

PA6/66
23 Mpa
PA6/66-GF
15 Mpa
-35%

Competitor 4

20% GF by weight

PA6
28 Mpa
PA6-GF
21 Mpa
-25%

Material Development

If your application requires a specific material that is not yet available in the market, consider our custom development service. With our talented material scientists and application engineers, we are ready to develop the necessary materials to enable your unique application.



Material development

-Twin-screw compounding
-Single-screw extrusion
-Torque rheometry
-Wet chemistry
-Other polymer processing equipment

Testing and characterization

-Thermal characterization (DSC, softening point)
-Mechanical testing (tensile, 3-point bending)
-Optical microscopy
-Capillary rheometry
-FTIR-ATR

3D Printing

-3D printing
-Post-processing
-Application development

Our state-of-the art R&D facilities allow us to engineer materials at different levels and fully optimize them for 3D printing. Our goal is to deliver materials with the right combination of properties/functions, processability and form to suit your needs!

Application

Processability technologies

Printing thechnologies
Post-processing
Other

Properties & functions

Mechanical
Thermal
Electrical
Other

Form

Pellet
Filament
Powder
Other

Polymaker products

PolyLite™

PLA
PETG
ABS
PC
ASA

PolyMax™

PLA
PETG
PC

PolyFlex™

TPU95

PolyMide™

CoPA
PA6-CF
PA6-GF

PolyDissolve™

S1

Specialty

PolyWood™
PolySmooth™
PolySupport™
PolyCast™

Hardware

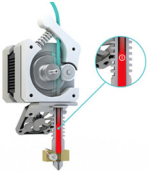
PolyBox™
Polysher™

More products coming soon...

Technologies

JAM-FREE™

Regular PLA



With Jam-Free™

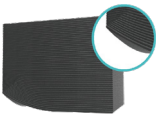
ASH-FREE™

Without Ash-Free™
Ash content: 0.5%

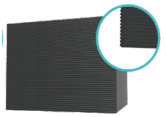
With Ash-Free™
Ash content: 0.003%

WARP-FREE™

Regular Nylon



With Warp-Free™



STABILIZED FOAMING™

Wood

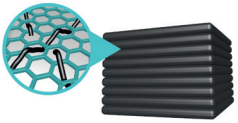
Stabilized Foaming™

LAYER-FREE™

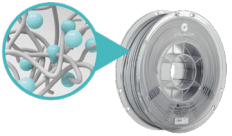
Rough surface

With Layer-Free™

FIBER ADHESION™



NANO-REINFORCEMENT



About Polymaker

Our Values

Customer Oriented

Responsible

Entrepreneurial

Embracing Innovation

Mission

Polymaker is committed to lowering the barriers to innovation and manufacturing, by continuously developing advanced 3D printing material technologies for industries and consumers.

Contact us

For any inquiries please contact:

inquiry@polymaker.com

For technical support please contact:

support@polymaker.com


polymaker